

Fig. 1



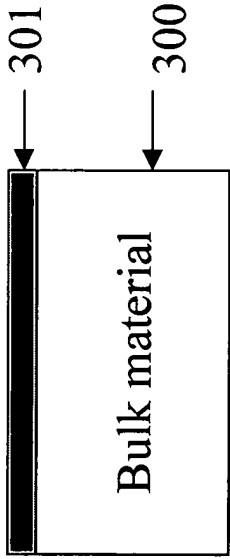


Fig. 3A

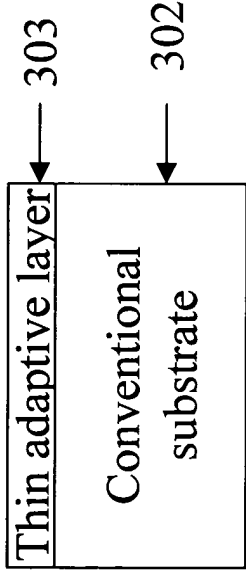


Fig. 3B

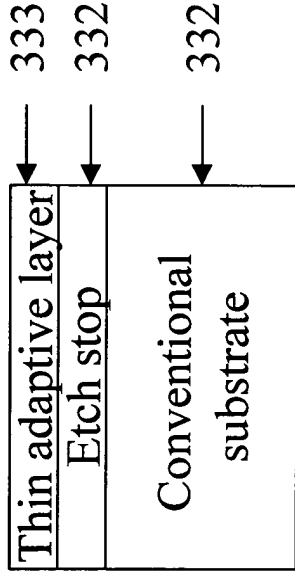


Fig. 3C

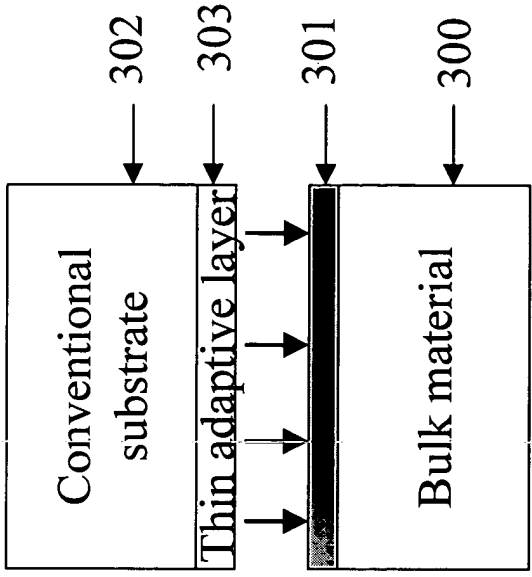


Fig. 3D

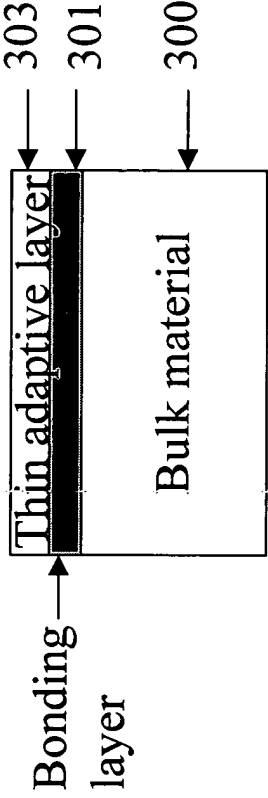


Fig. 3E

FIG. 4A is a schematic diagram of a substrate assembly 400. The assembly includes a conventional substrate 402, a thin adaptive layer 408, and a carrier substrate 400. The thin adaptive layer 408 is positioned between the conventional substrate 402 and the carrier substrate 400. A bonding layer 403 is located between the thin adaptive layer 408 and the carrier substrate 400. Arrows 404 indicate the direction of bonding or adhesion between the thin adaptive layer 408 and the carrier substrate 400.

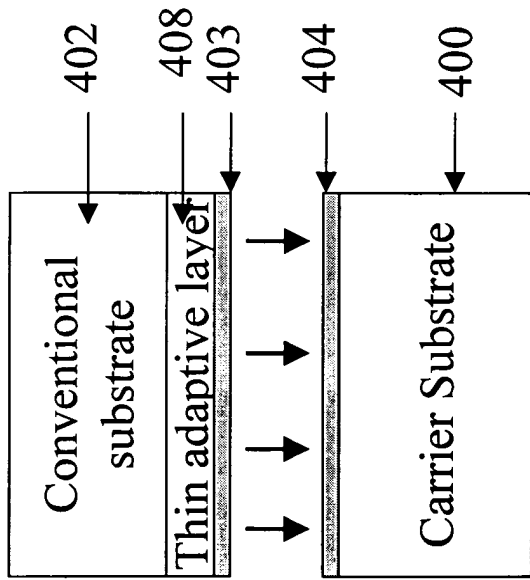


Fig. 4A

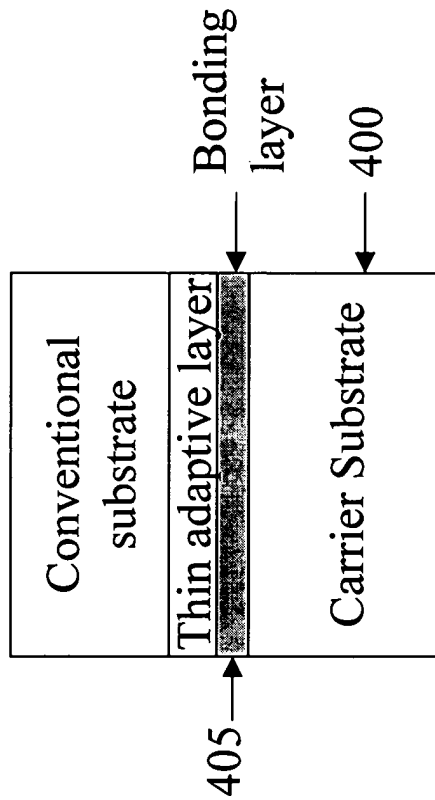


Fig. 4B

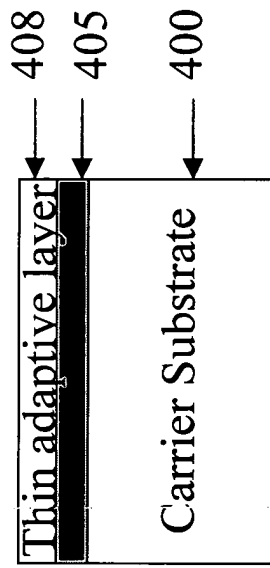


Fig. 4C

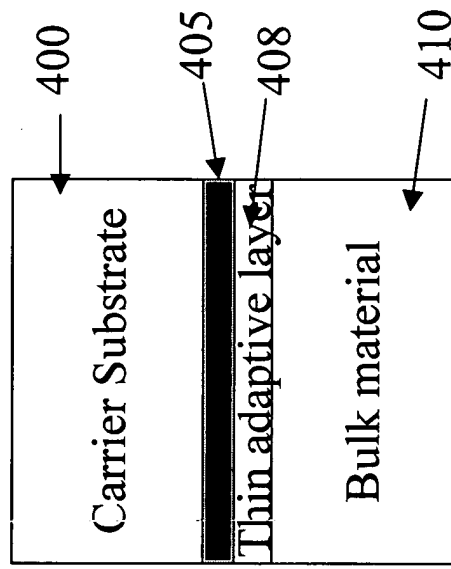


Fig. 4D

epi Side Down

epi Side Up

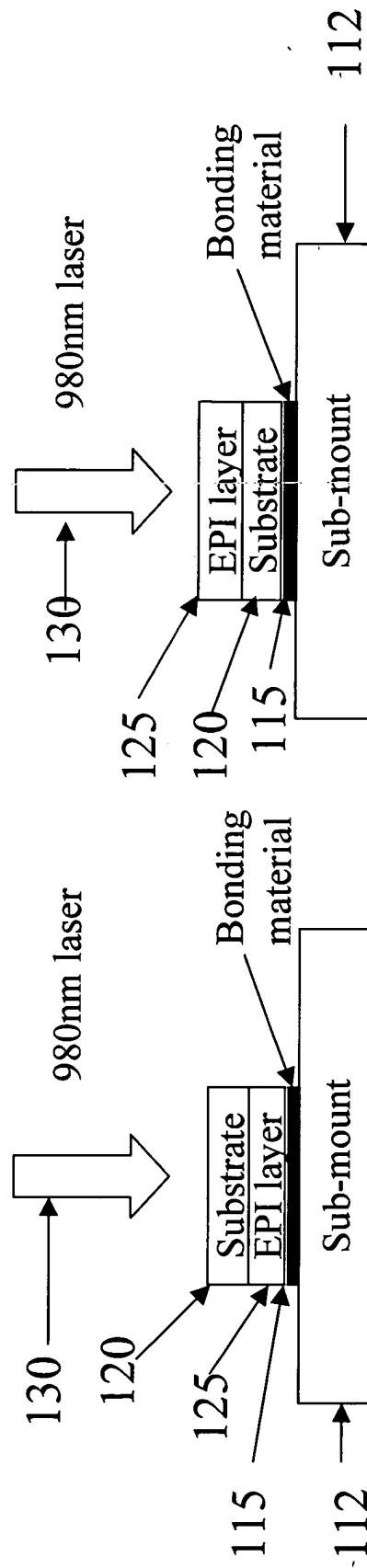


Fig. 5